

# Material Composition Data



Product: CM9V-T1A

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CM9V-T1A -					Sub-Assembly
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	% by mass
Electrodes	Gold	Au	7440-57-5	0.005	100.00
Gold Bump	Gold	Au	7440-57-5	0.009	100.00
Housing	Ceramic	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	1.260	100.00
Metal Lid	Kovar Lid	Fe	7439-89-6	0.353	52.45
	Kovar Lid	Ni	7440-02-0	0.193	28.68
	Kovar Lid	Cr	7440-47-3	0.120	17.83
	Nickel plating	Ni	7440-02-0	0.007	1.04
Resonator	Quartz	SiO <sub>2</sub>	14808-60-7	0.120	100.00
Seal	Solder Preform	Au	7440-57-5	0.120	80.00
	Solder Preform	Sn	7440-31-5	0.030	20.00
Terminations	Gold	Au	7440-57-5	0.010	5.00
	Molybdenum	Mo	7439-98-7	0.160	80.00
	Nickel	Ni	7440-02-0	0.030	15.00
<b>Total Mass:</b>				<b>2.417 mg</b>	

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